07-25-	2006	
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Executive Order 9424, Confirmatory License Mother Termination of Security Interest		
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A. Patent Application No.(s)	B. Patent No.(s)	•
attached Schedule		
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5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of involved:382	applications and patents
Name: Laura Konrath	7. Total fee (37 CF	R 1.21(h) & 3.41) \$ 15,280
Internal Address:	Authorized to t	e charged by credit card
	Authorized to t	e charged to deposit account
Street Address: 35 W. Wacker Dr.	Enclosed	
		(government interest not affecting title)
City:Chicago	8. Payment Inform	1
State:Zip:60601		Last 4 Numbers Expiration Date
Phone Number: 312-558-6352	b. Deposit Acco	upt Number _ 232428
Fax Number:		- Fairth
Email Address: lkonrath@winston.com	Authorized U	ser wallie According to the Co
9. Signature: Aum Am	Carl	1/19/06
Signature		(ORIGINALLY Date BATITTED
<u>Laura ⁷Konrath</u> Name of Person Signing		number of pages including cover , attachments, and documents:
Documents to be recorded (including cover sheet Mail Stop Assignment Recordstion Services, Director o		

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PAGE 3/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

Continuation Item 4

All patents are encumbered with security interests.

U.S. PATENT APPLICATIONS

Application	Filed	Title
08/268,094	06/28/94	Epoxy acrylates
08/589,435	01/22/96	Curable epoxy resin formulation
08/876,550	06/16/97	Preparation of mouldings by the automatic pressure
		gelation technique using a one component
		composition
09/002,847	01/05/98	Curable epoxy resin composition comprising fillers
09/787,220	03/16/01	Method for producing etched circuits
09/787,221	03/16/01	Method for producing multi-layer circuits
09/856,116	05/17/01	Crosslinking agent for carboxyl*containing polymers
		in heat-curable systems
09/857,684	06/07/01	Hydrophobic epoxide resin system
09/868,817	06/21/01	Production of photoresist coatings
09/890,213	07/26/01	Melamine-modified phyllosilicates
09/932,731	08/17/01	Epoxy acrylates
09/936,706	09/14/01	Hardenable composition with a particular combination
		of characteristics
09/937,001	09/19/01	Matting agents for thermally curable systems
10/019,910	11/09/01	Photosensitive composition
10/031,108	01/10/02	Nanocomposites
10/031,134	01/14/02	Filler mixtures
10/031,135	03/29/02	Curable composition
10/031,983	01/25/02	Amine hardener for epoxy resins
10/208,460	07/30/02	Powder coating carboxyl polyester or (poly)
		methacrylate and cycloaliphatic polyepoxide
10/416,978	05/15/03	Positive type photosensitive epoxy resin composition
		and printed-circuit board using the same
10/433,137	05/29/03	Filled epoxy resin system having high mechanical
		strength values

PAGE 4/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNI5:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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U.S. PATENTS ISSUED

Patent	Granted	Application	Filed	Title
RE32,745	09/06/88	07/021,151	03/03/87	Polymeric resins derived from 1-oxa-3-aza
1	1			tetraline group-containing compounds and
				cycloaliphatic epoxides
4,474,929	10/02/84	06/538,033	09/30/83	Polyglycidyl ethers of branched novolacs
4,528,359	07/09/85	06/610.896	05/16/84	Adducts of epoxy resins and amino-substituted
				aromatic sulfonic acid amides
4,540,769	09/10/85	06/654,342	09/25/84	Preparation of n-glycidyl compounds
4,541,894	09/17/85	06/614,760	05/29/84	Metallizable essentially isotropic polymeric
4,544,623	10/01/85	06/573.098	01/23/84	substrates well adopted for printed circuits Photosensitive coating composition and the
4,344,023	10/01/03	00/3/ 3,030	01/25/04	use thereof for protective purposes
4,594,291	06/10/86	06/716,279	03/25/85	Curable, partially advanced epoxy resins
				control politicity automoco chowy testing
4,604,317	08/05/86	06/737,591	05/24/85	Curable compositions containing a
				polyepoxide and a halogenated bisphenol
4,604,452	08/15/86	06/789,678	10/21/85	Metal carboxylate/alkylphenol curing catalyst
			l	for polycyanate esters of polyhydric phenois
4,607,091	08/19/86	06/774,433	09/10/85	Polymeric resins derived from 1-oxa-3-aza
				tetraline group-containing compounds and
				cycloaliphatic epoxides
4,608,300	08/26/86	06/619,751	06/11/84	Fibre composite materials impregnated with a
4.608.434	08/26/86	06/789.679	10/21/85	curable epoxide resin matrix Metal carboxylate/alcohol curing catalyst for
4,000,404	00/20/00	00//05/0/5	10/21/03	polycyanate ester of polyhydric phenol
4,614,674	09/30/86	06/730,121	05/03/85	Powder coaling compositions for the
.,	0,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	007.007.00	03/03/02	preparation of matt coatings
4,621,159	11/04/86	06/773,685	09/09/85	Brominated hydroxy aromatic compounds
4,624,912	11/25/86	06/698,952	02/06/85	Thermally transferable layers of radiation
			1	sensitive epoxy resins used to prepare
				protective coatings and relief images
4,632,900	12/30/86	06/708,998	03/07/85	Process for the production of images after
	{ {		ł	electrodeposition of positive photoresist on
4,654,447	03/31/87	06/831.400	02/20/86	electrically conductive surface Process for the preparation of
1,034,447	(2) (2) (2) (2) (2) (2) (2) (2) (2) (2)	00001,400	02/20/00	tribromotetramethylbiphenol and related
1			1	compounds
4,656,292	04/07/87	06/745,748	06/17/85	2,3-dimethylmaleimido-alkyl haloacetates
4,661,578	04/28/87	06/801,360	11/25/85	High temperature epoxy resin composition
	•			with reduced viscosity
4,661,644	04/28/87	06/812,476	12/23/85	Brominated Epoxy Aromatic compounds
4,666,954	05/19/87	06/642,909	08/21/84	Process for the preparation of prepregs, and
				the reinforced composite materials which can
				be obtained therewith
4,666,997	05/16/87	06/773,724	09/09/85	Heat-curable mixture containing substitute
	1			bicyclo(2.2.1.)Hept-5-ene-2, 3-dicarboximide
4 660 710	05 26 /07	6/780,160	1 00/06/06	and polymaleimide, and the use thereof
4,668,718	05/26/87	00//00,100	09/26/85	Self-extinguishing, track-resistant epoxy resin
4,668,807	05/26/87	06/807,566	12/11/85	Process for reducing the content of
4,000,007	05/20/07	00/00/,300	1211/05	hydrolyzable chlorine in glycidyl compounds
4,672,103	06/09/87	06/829.361	02/14/86	Non-sintering epoxy resins prepared from
-1,072,103	00/05/07	00/027,001	02/14/00	triglycidyl ethers and epihalohydrins
4,681,923	07/21/87.	06/831,685	02/21/86	Modified guinone-diazine group-containing
-1,001,923	0,72,007,	00/031/003	1 0221000	phenolic novolak resins
4,684,700	08/04/87	06/829.364	02/14/86	Advanced epoxy resins prepared from
<i>,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,</i>) · · ·	00020,004	1 00 14/00	triglycidyl ethers and dihydric phenols
		<u></u>		I complete you could and any any and any

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PAGE 5/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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Patent	Granted	Application	Filed	Title
4,684,752	08/04/87	06/858,473	04/30/86	Di-ortho-substituted di-meta-halogenated para- halomethylphenois
4,689,378	08/25/87	06/809,444	12/16/85	Stable imide-containing composition from diamino phenyl indane-bis-maleimide and alkenyl phenol
4,709,008	1/24/87	06/880,529	06/30/86	Blend of tris (cyanatophenyl) alkane and bis(cyanatophenyl) alkane
4,722,983	02/02/88	06/939,213	12/08/86	Process for the preparation of glycidyl compounds
4,731,423	03/15/88	06/896,480	08/13/86	Meta-halo-phenolic alkylation products and epoxy systems
4,737,553	04/12/88	06/912,722	09/29/86	Advanced resins from diglycidyl ethers of de- secondary alcohols and dihydric phenols
4,740,584	04/26/88	06/904,610	09/08/86	Blend of dicyanate esters of dihydric phenois
4,742,141	05/03/88	06/929,837	11/13/86	Imido polymer from bis imide and alkenyloxyaniline
4,749,767	06/07/88	07/059,366	06/08/87	Stable imide-containing composition from diaminophenylindane-bis-imide, amine and alkenyl phenol or ether (chaudhari)
4,756,756	07/12/88	06/705,726	02/26/85	Forming of thick-layer, hybrid electronic- printed circuits (cassat)
4,785,075	1 1/1 5/88	07/078,037	07/27/87	Metal acetylacetonate/alkylphenol curing catalyst of polycyanate esters of polyhydric phenols (shimp)
4,799,996	01/24/89	07/078,166	07/27/87	Metallizable substrate composites and printed circuits produced therefrom (Cassat)
4,800,215	01/24/89	07/170,217	03/15/88	Compositions prepared from dialkanolamines and triglycidyl ethers of trisphenols (Bertram; Myles; Kubisiak)
4,826,927	05/02/89	07/000,255	01/02/87	Mixtures containing polymides alkenyphenols and either epoxide group-free adducts or another polymide (Schmid)
4,829,138	05/09/89	07/159,907	02/24/88	Novel heat-stable siloxane/bismaleimido polymers (Barthelerny)
4,839,440	06/13/89	07/134,043	12/17/87	N,N'-bis(maleimide)salkenyloxyanaline copolymerizates (Barthelemy)
4,839,442	06/13/89	07/210,175	06/20/88	Low viscosity noncrystalline dicyanate ester blends with prepolymers of dicyanate esters (Craig)
4,845,172	07/04/89	07/186,753	04/26/88	Co-advanced resins from copolymers of polyethers of polyhydric phenols and diglycidyl ethers of di-secondary alcohols (Brytus)
4,847,233	04/11/89	07/228,469	06/05/88	Metal acetylacetonate/alkylphenol curing catalyst for polycyanate esters of polyhydric phenols (Shimp)
4,847,343	07/11/89	07/166,501	03/10/88	Heat-resistant maleimido copolymers
4,847,344	07/11/89	07/166,482	03/10/88	Novel heat-resistant maleimido copolymers
4,848,533	07/18/89-	07/243,181	09/14/88	Apparatus for conveying panels (Martin)
4,849,320	07/18/89	07/045,022	04/30/87	Method of forming Images (Irving)
4,849,490	07/18/89	07/159,911	02/24//	Novel bis(Maleimide)/polysiloxanes
4,857,607	08/15/89	07/195,312	05/18/88	EpoxIdized polycycloacetals (Cotting)
4,861,438	08/29/89	07/297,372	01/17/89	Method of making patterns (Banks)
1,885,354	12/05/89	07/258,542	10/17/88	Epoxy resin compositions (Hofer)
4,892,925	01/09/90	07/300,460	01/23/89	Process for preparing phenolic hydroxyl- containing compounds from 2,6-Dibromo-3,5
1 000 755	+ 01/25/25		1 101-1-	dialkyl-4-hydroxybenzyl ethers
4,895,755	01/23/90	07/259,449	10/14/88	Halogenated Advanced Epoxy resins



PAGE 6/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID;Winston Strawn * DURATION (mm-ss):18-38

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Patent	Granted	Application	Filed	Title
4,914,185	04/03/90.	06/851,996	04/14/86	Adducts of metabrominated phenols and polyfunctional epoxides (Wang et al.)
4,923,520	05/08/90	07/251,995	09/30/88	Spherical fused silica and its use in fillers an resin compositions (Anzai & Hamabe)
4,926,789	05/22/90	07/252,302	10/03/88	Transport apparatus for boards (Wenger)
4,931,545	06/05/90	07/347,251	05/03/89	Flame retardant polycyanate ester blend (Shimp)
4,940,848	07/10/90	07/269,862	11/10/88	Stable solutions f prepolymens of thiodi(phenylcyanate) and laminating metho employing same (Shimp)
4,950,728	08/21/90	202,544	06/06/88	Thermally stable (imide/amide)(urea/siloxan block copolymers
4,957,946	09/18/90	07/202,739	06/03/88	Cationically polymerizable mixtures containing metallocene complex salt of cert carboxylic or sulfonic acids (Meier)
4,962,178	10/09/90.	07/266,555	11/03/88	Novel polysiloxane - polyurethanes and contact lens thereof
4,963,300	10/16/90	07/279,747	12/05/88	Process for the preparation of laminates
4,973,648	11/27/90	07/411,949	09/25/89	Epoxy resin compositions (Hofer)
4,973,649	11/27/90	07/319,306	03/03/89	Hindered diamine/imido prepolymers
4,975,500	12/04/90	07/440,149	11/22/89	Adducts of metabrominated phenols and polyfunctional epoxides
4,978,604	12/18/90	07/208,524	06/20/88	Process for forming images (Banks)
4,978,809	12/18/90	07/434,150	11/13/89	Meta-halogenated dibenzylphenols
4,992,488	02/12/91	07/403,845	09/01/89	Glass fibre-reinforced epoxide resin mouldi composition and its use (Ruf)
4,992,572	02/12/93	07/258,544	10/17/68	Process for the preparation of organometall compounds (Desobry)
4,994,346	02/19/91	07/221,846	07/20/88	Negative photoresist based on polyphenols and selected epoxy or vinyl ether compour (Meler)
4,996,285	02/26/91	07/420,723	10/11/89	Imide/epoxy thermosetting compositions (Arpin)
5,002,858	03/26/91	07/434,599	11/07/89	Process for the formation of an image (Demmer)
5,006,626	04/09/91	07/411,951	09/25/89	Epoxy resin compositions (Hofer)
5,013,804	05/07/91	07/505,097	04/03/90	Curable mixtures containing a bismaleimid and a propenyl compound (Kramer)
5,013,814	05/07/91	07/462,252	01/09/90	Araliphatic sulfonium salts and their use (R
5,019,639	05/28/91	07/503,399	04/02/90	Novel epoxy resins (Hofer)
5,021,484	06/04/91	07/376,875	07/07/89	Fire retardant curable 1-oxa-3-aza tetraline (also termed "3.4-dihydro-1,3-benzoxazine derived resin composition (Schreiber)
5,028,668	07/02/91	07/549,177	07/06/90	Adducts of metabrominated phenols and polyfunctional epoxides
5,030,730	07/09/91	07/483,149	02/21/90	Curable mixtures (Munk)
5,034,503	07/23/91 •	07/598,126	10/16/90	Novel imido copolymers (Camberlin)
5,037,923	08/06/91	07/544,061	06/26/90	Novel imida Palymers (R. Arpin)
5,053,474	10/01/91.	07/426,850	10/26/89	Imido polymers (Camberlin)
5,068,309	11/26/91	07/501,231	03/29/90	Low temperature curable dicyanate ester of dihydric phenol composition (Shimp)
5,073,233	12/17/91	07/532,533	06704/90	Method of making a metallic pattern on a substrate (Banks)
5,073,478	12/17/91	07/439,724	11/20/89	Method of making a pattern (Banks)

PAGE 7/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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F	5,079,129	01/07/92	07/445,134	11/30/89	Negative photoresist based on polyphenols
1				1	and epoxy compounds or vinyl ethers (Roth))
		01/14/92	07/629.099	12/17/90	
	5,080,998	01114192	07/029,099	12/1//90	Process for the formation of positive images utilizing electrodeposition of o-quinone
		1			diazide compound containing photoresist on
		1			conductive surface (Irving)
L L	5,082,952	01/21/92	06/867,113	05/27/86	Process for the preparation of metallocene
L				07/00400	complexes (Meler)
I	5,086,154	02/04/92	07/550,047	07/09/90	Linear aromatic poly/amideimide)s having latent maleimide end groups (Camberlin)
ł	5,087,688	02/11/92	07/541,237	06/20/90	Fibrous composite structure impregnated with
	,				a solvent-free curable epoxy resin matrix
					(Gruber)
	5,098,527	03/24/92	07/408,860	09/18/89	Method of making electrically conductive
					patierns (Banks)
	5,098,963	03/24/92	07/652,845	02/08/91	Adducts of metabrominated phenols and
					polyfunctional epoxides (Wang, Mendoza)
	5,112,440	05/12/92	07/601,162	10/22/90	Method for making metallic patterns (Banks)
	5,113,701	05/19/92	07/647.322	01/29/91	Transport device for boards having a sensitive
	5,115,701	V3/13/32	0/1047,322	01/23/31	surface especially for wet-coated circuit boards
					(Martin)
	5,113,785	05/19/92	07/590,902	10/01/90	Transport device for boards, especially those having a sensitive surface (Martin)
				}	naving a sensitive surrace (martin)
120	5,115,005	05/19/92	07/756,405	09/09/91	Phosphinic acid flame retardant (Horner)
16-	5,117,010	05/26/92	07/745,569	08/15/91	Process for the preparation of addition
	5,122,589	06/16/92	07/506,743	04/10/90	products of epoxides and alcohols (Cheng) Imido/siloxane bismaleimide/aromatic
	5,122,309	00/10/92	0//300,/43	04/10/90	diamine prepolymers (Camberlin)
	5,122,590	06/16/92	07/506,744	04/10/90	Imido/hindered diamine copolymers
					(Camberlin)
	5,124,233	06/23/92 06/23/92	07/202,765	06/03/88	Photoresist composition Imido polymers (R. Arpin)
	5,124,419 5,128,491	07/07/92	07/696,706	07/30/91	Process for the Preparation of Glycidyl Ethers
	J,120,451	0//0//22	0/1/ 50,0/2	07750751	of Di-secondary Alcohols with High Monomer
					Content
	5,130,406	07/14/92	07/496,557	03/19/90	Initiators for Materials which can be
	5,130,452	07/14/92	07/695,856	05/06/91	polymerized Cationically Phosphorus compounds and their use a flame
	3,130,432	07/14/32	0/1033,030	05/00/91	retardant for polymers
	5,132,346	07/21/92	07/741,389	08/07/91	Fame retardant compositions of halogen-free
		Į			polymers containing cyclic phosphate or
		00/04/00			thiophosphate flame retardants
	5,136,110.	08/04/92	07/626,597	12/12/90	Process for the preparation of bisphenols (Walters, Richey, Tasset)
	5,149,767.	09/22/92	07/595,918	10/11/90	Thermosetting mixtures utilizing araliphatic
	3,(-13), 611			10/11/20	sulfonium salts.
	5,149,841.	09/22/92	07/694,525	05/01/91	N,N,N',N'-tetracycidyl-4,4,'-
	L	L	1	L	diaminodiphenylmethanes
	5,149,863	09/22/92	07/744,065	08/12/91	Low temperature curable dicyanate esters of
	C 153 101	10/06/63	07/07 204	06/12/00	dihydric phenols Photoresist
	5,153,101. 5,162,574.	10/06/92	07/537,394	06/13/90	Bix(4-cyanatophenyl)-1,1-ethane
	5,179,179	01/12/93	07/874,782	04/27/92	Initiators for materials which can be
				S STILLING	polymerized cationically
	5,183,869	02/02/93	07/699,541	05/14/91	Hardenable compositions
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PAGE 8/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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	Patent	Granted	Application	Filed	Title
	5,198,516	03/30/93	07/730,537	07/16/91	Thermally stable bisimido/P-allylaniline
	5.200,452	04/06/93	07/791,817	11/18/91	copolymers
	5,200,432	04/00/95	0/// 91,01/	11/10/91	Fire retardant curable 1-oxa-3-azatetraline (also termed "3,4-dihydro-1,3-benzoxazine")
					derived resin composition
	5,206,338	04/27/93	07/790,023	11/05/91	N,N"-bis(maleimide)/hindered diamine
$\Lambda \in \mathcal{A}$					copolymerizate
	5,208,110	05/04/93	07/368,452	06/19/89	Security cards
	5,221,723	06/22/93 07/20/93	07/864,146	04/06/92	Thermally stable bisimido copolymerizates
	5,229,485 5,236,746	08/17/93	07/766,467 07/908,604	09/26/91 06/29/92	Soluble polyimides
	5,230,740	00/1//33	0/1500,004	00/29/92	Curtain coating process for producing thin photoimageable coatings
					photomageaute coatings
	5,239,093	08/24/93	07/930,114	08/14/92	Process for the preparation of addition
					products of epoxides and alcohols
	5,240,981	08/31/93	07/709,905	06/03/91	Flame retardant polyimide system
	5,245,048	09/14/93	07/805,430	12/11/91	Production of glycidyl compounds
	5,247,113 5,262,501	11/16/93	07/638,602 07/881,587	01/07/91 05/12/92	Araliphatic sulfonium and their use
	5,272,227	12/21/93	07/747,594	08/20/91	Mixtures of spiroheptadienes
		12121133	0/// 1//374	00/20/91	Adducts of hydroxyl-group containing epoxy reins and isocyarlates and use thereof
	5,280,069	01/18/94	07/693,874	04/30/91	Nglycidyl compound
	5,284,968	02/08/94	07/769,356	09/30/91	Process for preparing bis (4-cyanatophenyl)-
		aci .			1,1-ethane
	5,286,611	02/15/94	07/916,933	07/20/92	Photoresist
	5,290,624	03/01/94	07/872,745	04/22/92	Heat-conductive adhesive films, laminates
					with heat-conductive adhesive layers and the
	5,294,683	03/15/94	07/952,123	09/28/92	use thereof Solid compositions of polyglycidyl
			0,1992,129	0,720,72	compounds having a molecular weight of less
					than 1500
	5,296,567	03/22/94	07/863,638	04/06/92	Thermocurable compositions
	5,300,380	04/05/94	07/947,899	09/17/92	Process for the production of relief structures
					using a negative photoresist based on
					polyphenols and epoxy compounds or vinyl ethers. (Roth, Mejer)
					cures. (Kolli, Melel)
	5,304,662	04/19/94	08/000,900	01/06/93	Polyglycidyl compounds (Michael R. Thoseby;
	5 3 3 4 3 3	26/4 / 20			Bryan Dobinson
	5,321,103	06/14/94	08/131,272	10/04/93	Compositions comprising aminoplast resins
					and solid colloidal condensation polymers (Alfred Renner)
	5,322,907	06/21/97	07/856,240	03/25/92	Hardeners for powder coating compositions
			0	05125.72	based on polyester resins (Cotting; Gottis)
	5,331,068	07/19/94	08/109,415	08/19/93	Adducts of diaminodiphenyl sulfone
					compounds as hardeners for epoxy resins
	5,332,781	07/26/94	08/080,797	06/22/93	Storage-stable suspension of tougheners in
	6 120 627	08/23/94	07/070 160	1.1.1.	epoxy resin hardeners
	5,339,537	00/23/94	07/973,469	11/09/92	Continuous drier for flat piece material
	5,342,903	08/30/94	08/055.656	04/30/93	Process for the Preparation of adducts of
	0,0 12,505		00,000,000	04/30/93	epoxides and alcohols
	5,344,635	09/06/94	08/011,930	02/01/93	Filler for heat-conductive plastics materials
	5,352,831	10/04/94	07/914,158	07/14/92	Oligomeric cyanoguanidines
	5,359,020	10/25/94	07/701,264	05/16/91	Hardenable compositions comprising
		ľ		1	bismaleimides alkenylphenols and phenol
	-				diallyl ethers
	5,362,835	11/08/94	07/804,308	12/09/91	Production of compounds
169	5,362,849	11/08/94	08/147,705	11/04/93	N-Glycidyl compound
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PAGE 9/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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ľ	5,366,947	11/22/94	07/931,755	08/18/92	Initiators for materials which can be
					polymerized cationically
	5,371,115	12/06/94	07/870,156	04/15/92	Cationically polymerizable compositions
ļ	6 371 350	12/06/04	00/041 210	016863	containing iron metallolene salt
H	5,371,259 5,374,697	12/06/94 12/20/94	08/046,350 08/091,803	04/08/93	fron (II) metallacene saits Selected novel sulfanium compounds
	2,274,077	12/20/94	00071,003	0//14/33	particularly suitable as initiators for the
					thermal cure of cationically polymerisable
1					materials
[5,382,710	01/17/95	07/922,450	07/30/92	Aromatic polyhydroxy compounds and
- 1					process for the preparation thereof (Walters,
	5,391,681	02/21/95	08/068,376	05/27/93	Richey, Tasset) Curable compositions based on epoxy resins
	3,391,001	02121135	00/000,370	03/2/193	or mixtures of epoxy resins and
					polyisocyanates containing trisimidazoly!
					triazines
	5,399,416	03/21/95	08/159,389	11/30/93	Heat-conductive adhesive films, laminates
					with heat-conductive adhesive layer and the use thereof
	5,403,907	04/04/95	08/104,048	02/14/92	Prepolymers having imide groups
	5,412,065	05/02/95	08/045,395	04/09/93	Polymide oligomers
	5,420,312	05/30/95	07/979,011	11/20/92	Glycidyl ether from alcohol and
					epichlorohydrin
10/	5,420,342	05/30/95	08/154,642	11/19/93	Process for preparing bis (4-cyanatophenyl)-
190	E 131 373	06/13/95	08/268.091	06/28/94	1,1-ethane
	5,424,373	00/13/95	08/268,091	06/28/94	Oligometic cyanoguanidines hardeners for epoxy resins
	5,426,150	06/20/95	08/241,212	05/10/94	Preparing suspension of epoxy resin hardener
					and toughener
	5,443,911	08/22/95	08/150,975	11/12/93	Curable resins comprising halogenated epoxy
					resins and 1-oxa-3-AZA tetraline compounds, method for preparing and use of resins
	5,451,362	09/19/95	08/154,201	11/18/93	Moulding process
]			
	5,457,168	10/10/95	08/384,793	02/13/95	Solid compositions of polyglycidy!
					compounds having a molecular weight of less than 1500
	5,470,896	1 1/28/95	08/376,539	01/20/95	Storage-stable solutions of accelerator systems
	5,470,920	11/28/95	08/122,600	04/03/92	impregnating solutions based on at least one
	-,				reactive thermoplastic poly (imide - amide)
					oligomer and a coreactant; which can e used
	l	ļ			especially for the production of
	5,478,915	12/26/95	08/175,817	12/30/93	preimpregnated intermediate articles
	5,494,944	02/27/96	08/292,658	08/18/94	Polyimide oligomers Hardenable composition and its use
	5,501,942	03/26/96	08/304.643	09/12/94	Photosensitive composition containing water
					as solvent or dispersant
	5,503,936	04/02/96	08/371,645	01/12/95	N-alkyl-n'-aryl-p-phenylenediamines as
			<u> </u>	I	modifiers for epoxy resins
	5,505,895	04/09/96	08/166,749	12/14/93	Process for making moulded articles of epoxy
	5,506,313	04/09/96	08/301,468	09/07/94	resin compositions Phosphorus-containing flameproofing agents
	5,506,313	04/09/96	00/301,408	09/07/94	for epoxy resin materials
	5,512,372	04/30/96	08/256,376	01/13/93	Epoxy resin composition and applications, in
	1				particular in composite structures using
	1	1		1	imidazole/polyamine mixture
	5,521,261	05/28/96	08/250,125	05/27/94	Epoxy resin mixtures containing advancement
					catalysts
	5,523,044	06/04/96	08/259,642	06/14/94	Process for molding epoxy resins with coarse
		- L	1		decorative particles

PAGE 10/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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Patent	Granted	Application	Filed	Title
5,523,362	06/04/96	08/412,181	03/28/95	Oligomeric cyanoguanidines
5,525,685	06/11/96	07/706,683	05/29/91	Epoxy resin compositions
5,541,282	07/30/96	08/336,597	1 1/09/94	Aromatic polyhydroxy compounds and process for the preparation thereof
5,543,572	08/06/96	08/377,719	01/24/95	Monocarboxamides of polyamines
5,552,459	09/03/96	08/240,791	05/10/94	Highly filled epoxy casting resin composition
5,565,500	10/15/96	08/310,452	09/22/94	Cationically polymerizable mixtures containing selected metallocene complex sal as curing agents
5,567,237	10/22/96	08/259,641	06/14/94	Continuous drier for board-shaped piece material and coating installation comprising such a continuous drier
5,569,734	10/29/96	08/432,112	05/03/95	Curable epoxy resin mixtures containing me
5,576,399	1 1/19/96	08/268,095	06/28/94	Epoxy acrylates
5,591,811	01/07/97	08/527,132	09/12/95	1-imidazolylmethyl- 2-naphthols as catalysts for curing epoxy res
5,597,886	01/28/97	08/512,044	08/07/95	Heat-curable epoxy resin systems having a good reactivity/stability ratio
5,606,013	02/25/97	06/948,278	12/31/86	Polyamic acids and polyimides
5,614,126	03/25/97	08/449,144	05/24/95	Solventless curable resin composition in particular for the fabrication of prepregs
5,614,606	03/25/97	06/948,279	12/31/86	Polyamic acids and polyimides
5,616,633	04/01/97	08/303,904	09/09/94	Liquid epoxy resin compositions
5,633,341	05/27/97	08/211,297	03/30/94	At room temperature crosslinkable compositions, and methods of their manufacture and use
5,637,148	06/10/97	08/529,467	09/18/95	Apparatus for coating board-shaped piece material on both sides
5,637,387	06/10/97	08/462,438	06/02/95	Storage-stable advanced polymaleimide compositions
5,652,322	07/29/97	08/715,054	09/17/96	Heat-curable epoxy resin systems having a good reactivity/stability ratio
5,668,227	09/16/97	08/613,393	03/11/96	Cyclohexyl-group-containing glycidyl ethers
5,691,006	11/25/97	08/568,092	12/06/95	Solder resist coating form photosensitive composition containing water as solvent or dispersant
5,703,343	12/30/97	08/545,746	11/01/95	Process and plant for the manufacture of sol castings from an essentially liquid reactive medium, and oven for heating an essential liquid medium
5,705,541	01/06/98	08/647,077	05/08/96	High gloss molded articles of curable epoxy resin composition comprising fillers
5,789,482	08/04/98	07/952,122	09/28/92	Epoxy resin with anhydride, roughener and active hydrogen-containing compound
5,821,318	10/13/98	08/779,181	01/06/97	Hardener composition for epoxy resins
5,844,047	12/01/98	08/838,765	04/10/97	Single component, heat curing composition which are stable when stored at room temperature and which comprise polymers containing anhydride groups and powdered crosslinking agents, and their method of manufacture and use
5.847.376	12/08/98	08/840,551	04/15/97	Process and plant for the manufacture of so castings from an essentially liquid reactive medium, and oven for heating an essential liquid medium
5,872,163.	02/16/99	08/738,561	10/28/96	Liquid epoxy resin composition containing wollastonite and calcite

PAGE 11/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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	Patent	Granted	Application	Filed	Title
	5,900,204	05/04/99	08/894,544	03/01/96	Production of thermoset pressure gelation castings
	5,904,888	05/18/99	08/973,649	06/18/96	Curable compositions
	5,906,784	05/25/99	08/959,502	10/28/97	Curable epoxy resin compositions
	5,908,668	06/01/99	08/991,523	12/16/97	Curtain coating apparatus having a planar deflector surface and method for using the
	5,939,242	08/17/99	08/757,391	11/27/96	same Positive Photoresist with an alkoxyalkyl ester
					group-containing (co)polymer and carboxyl- group containing (co)polymer
	5,942,371	08/24/99	06/714,633	09/13/96	Aqueous acrylic photopolymerisable compositions
	5,955,551	09/21/99	08/907,285	08/06/97	Polyglycidyl ethers of secondary alcohols, their preparation, and curable compositions containing them
	5,994,432	11/30/99	07/727,539	07/09/91	Storage-stable/clear solutions of poly(imideamides)
	5,994,475	11/30/99	08/886,308	07/01/97	Reaction products of amine and a carboxyl functional microgel
•	6,001,428	12/14/99	08/630,738	04/10/96	Solid epoxy resin compositions crosslinkable with UV rays
	6,001,902	12/14/99	09/048,821	03/26/98	Wollastonite-containing curable epoxy resin
	6,029,944	02/29/00	08/894,451	02/24/96	Casting device and an adapter for a casting device
	6,030,713	02/29/00	08/184,537	11/02/98	Electrical or Electronic Components Encapsulated with Liquid Epoxy Resins Containing a Mixture of Wollastonite and
	6,037,392	03/14/00	08/755,382	11/21/96	Calcite Fillers Core/shell particles, and curable epoxy resin composition
	6,045,972	04/04/00	09/320,919	05/27/99	Coating method using aqueous photopolymerizable compositions
	6,048,946	04/11/00	09/137,371	08/20/98	Hydrophobic epoxy resin systems
	6,054,536	04/25/00	09/124,139	07/29/98	Epoxy resin compositions
	6,066,435	05/23/00.	09/075,638	05/11/98	Liquid photosensitive composition
	6,090,891	07/18/00	09/075,639	05/11/98	Carboxyl-containing polymer(s) with (2-oxo- 1,3-dioxolan-4-ylmethyl groups-containing compound(s)
	6,093,493	07/25/00	09/100,003	06/17/98	Method for the coating or encapsulation of fluidizable substrates
	6,103,157	0815/00	09/100,005	06/17/98	Process for Impregnating electrical coils, and selected epoxy resin composition for carrying out the impregnation
	6,103,825	08/15/00	09/070,662	04/30/98	Epoxy resin pre-advanced with carboxyl- containing polyester and advanced with bisphenol
	6,107,451	08/22/00	09/177,141	10/21/98	Hardener for anhydride group-containing polymers
	6,111,015	08/29/00	08/391,329	02/21/95	Core/shell polymer toughener suspended in epoxy resin
	6,112,885	09/05/00	09/035,310	03/05/98	Transport apparatus for thin, board-shaped substrates
250	6,117,952	09/12/00	09/019,636	02/06/98	Powder coating composition
σ'	6,132,641	10/17/00	09/077,484	05/29/98	Composition and support material comprising poly(9,9'-spiro-bisfluorenes)
	6,136,922	10/24/00	08/690,373	07/26/96	Composition of carboxyl-containing poly(meth)acrylate, carboxyl-terminated
Ĺ			<i>.</i>		polyester and epoxy resin

PAGE 12/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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	6,165,558	1 2/2 6/00	09/101,789	07/16/98	Storage-stable moulding powder based on epoxy resins
E	6,169,158	01/02/01	09/298,573	04/23/99	Polyglycidyl compounds
	6,174,985	01/16/01	09/230,410	01/25/99	Epoxy resins with n-esters substituted imidazoles
ſ	6,180,009	01/30/01	09/101,095	02/23/98	Method of filtering the organic solutions arising in the production of circuit boards
	6,180,693	01/30/01	09/390,122	09/03/99	Core/shell particles, and curable epoxy resin compositions comprising same
Í	6,194,490	02/27/01	09/253,162	02/19/99	Curable composition comprising epoxidised natural oils
	6,197,849	03/06/01	09/248,649	02/11/99	Organophilic phyllosilicates
[6,197,861	03/06/01	09/230,395	01/27/99	Stabilisation of paints with spiroindane derivatives
	6,242,638	06/05/01	09/267,585	03/12/99	Cyanate esters having flame resistant properties (CIP filed 06/26/00 - 6,365,671)
[6,258,919	07/10/01	09/142,269	09/03/98	Curable epoxy resin compositions containing water-processable polyamide hardeners
	6,262,148	07/17/01	09/334,085	06/16/99	Novel phenalkamine curing agents and epoxy resin compositions containing the same
	, 6,265,487	07/24/01	09/016.619	01/30/98	Powder coating of carboxyl-containing poly(meth) acrylic resin and trans(cis)diglycidyl 1,4-
	6,271,463	08/07/01	09/327,859	Q6/18/99	Use of expandable epoxy systems for barrier materials in high voltage liquid-filled transformers
	6,274,673	08/14/01	09/376,797	08/18/99	Powder coating composition of epoxy resin mixture and carboxyl-containing
	6,277,929	08/21/01	09/380,449	03/07/97	Polymerizable Unsaturated Compounds, Curable Resin Compositions Containing the same, and Products of Curing thereof
	6,350,825	02/26/02	09/605,193	06/28/00	Reacting Diglycidyl, Bisphenol and monophenol with Catalyst and Mixing with Polygycidyl
	6,365,671	04/02/02	09/603,504	06/26/00	Compositions cyanate ester and aromatic compounds having improved heat release properties
770	6,380,445	04/30/02	09/567,348	05/09/00	Poly(9,9'-spirobisfluorenes), their production and their use
÷	6,399,277	06/04/02	09/214,053	12/28/98	Photopolymerizable thermosetting resin composition
	6,417,316	07/09/02	09/421,166	10/19/99	Curable epoxy resin compositions
	6,433,084	08/13/02	09/298,572	04/23/99	Powder coating
	6,437,045	08/20/02	09/697,331	10/25/00	Powder coating of carboxyl polyester or (poly) methacrylate and cycloaliphatic polyepoxide
;	6,455,662	09/24/02	09/728,991	12/4/00	Curable mixtures based on epoxy resins comprising imidazoles
	6,458,993	10/01/02	09/773,305	01/31/01	Cyanate esters having flame resistant properties
	6,465,601	10/15/02	09/787,165	06/15/01	Accelerators for hardenable systems
	6,479,596	11/12/02	08/652,394	05/23/96	Epoxy acrylates
	6,489,405	1 2/03/02	08/573,767	12/18/95	Epoxy resin formulation containing epoxy group-terminated polyesters
	6,517,895	02/11/03	09/719,803	03/12/01	Method of coating printed circuit boards or similar substrates
	6,528,594	03/04/03	09/743,501	01/10/01	Flowable granulates
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PAGE 13/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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Patent	Granted	Application	Filed	Title
6,555,601	04/29/03	09/465,866	12/16/99	Process for impregnating electrical coils, and selected epoxy composition for carrying out the impregnation
6,559,277	05/06/03	10/096,926	03/14/02	Poly(9,9'-spirobisfluorenes), their production and their use
6,562,410	05/13/03	09/743,378	01/08/01	Heat curable epoxy compositions
6,562,884	05/13/03	09/936,710	09/14/01	Epoxy resin compositions having a long shelf life
6,579,566	06/17/03	08/999,803	05/20/97	One-component epoxy resin system for trickle impregnation and hot dip rolling

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PAGE 14/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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All patents are encumbered with security interests.

### PATENT APPLICATIONS

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P	atons Number		Date logued
	Application	Filed	Title
	09/418,609	10/15/99	Method for filling and reinforcing honeycomb sandwich panels
1	<u>09/703,787</u>	11/01/00	Casting resin and process for the fabrication of resin molds
L	<u>09/762,908</u>	02/12/01	Pack for two-component product
L	09/762.909	02/12/01	Pack for two-component product and method of making it
L	<u>09/762,910</u>	02/12/01	Container and packaging method
	09/776.656	02/05/01	Liquid, radiation-curable composition, especially for stereolithography
İ	09/868.289	06/15/01	Thermosetting poly urethane/urea-forming compositions
ļ	09/953,250	09/17/01	Photosensitive diacrylate and dimethacrylate compositions
	09/986.815	11/13/01	Amine-modified epoxy resin reacted in presence of latent hardener
ſ	10/002.181	12/05/01	Method of treating an aluminum surface
	10/018.667	12/12/01	Process for the preparation of reaction products of cycloaliphatic epoxides with multifunctional hydroxy compounds
ł	10/031.134	01/14/02	Eiller mixtures
l l	10/069,164	02/20/02	Bonding of concrete parts
300	10/088,564	03/15/02	UV-curable compositions
<i>,</i> •••	10/125,508	04/19/02	Photocurable compositions containing reactive polysiloxane garticles
	<u>10/143,907</u>	05/14/02	Liquid, radiation-curable composition, especially for producing cured articles by stereolithography having high heat deflection temperatures
	10/167.436	<u>Q6/13/02</u>	Liquid radiation-curable composition, especially for producing flexible cured articles by stereolithography
	10/182.412	07/29/02	Epoxy resin composition
	10/225,830	08/21/02	Use of amino resins and catalyzing redox pairs in three dimensional printing applications
	10/258,204	10/18/02	Coherent insert
	10/283.233	10/30/02	Photocurable compositions with phosphite viscosity stabilizers
	10/332.597	01/10/03	High Functional polymers
	10/380,392	03/11/03	Seamless model and method of making a seamless model
	10/399,444	04/15/03	Three-dimensional structured printing
ĺ	10/416.101	04/25/03	High functional polymers

PAGE 15/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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### U.S. PATENTS ISSUED

Patent	issued	Application	Filed	Title
4,476,292	10/09/84	06/574,823	01/30/84	Castable polyurethane systems
4,540,750	09/10/85	<u>06/653.417</u>	09/24/84	Diethy toluene diamine hardener systems
4.659.779	04/21/87	06/847.371	04/02/86	Solid solution of amine and polymerized phenol as
				epoxy resin cure accelerator
4.701.378	10/20/87	<u>06/847,365</u>	04/02/86	Bonding process using curable epoxide resin adhesive
4,713,432	12/15/87	07/002.358	01/12/87	Solid solution of amine and polymerized phenol
4.734.332	03/29/88	07/002.355	Q1/12/87	Method for effecting adhesion using laminates from
				epoxy resins
4.866.133	<u>Q9/12/89</u>	07/095.725	09/14/87	Solid solutions of polymeric phenols and polyamines
				as epoxy curing agents
4.916.173	04/10/90	07/190.796	05/06/88	Polyurethane syntactic foam modeling stock
4.920.182	04/24/90	07/279.884	12/05/88	Epoxy resin compositions containing polyester
				flexibilizer and metallocene complex initiator
4.933.392	<u>96/12/90</u>	07/376,796	07/07/89	Curable epoxide resin compositions
4.952.645	08/28/90	07/287.581	12/16/88	Epoxide resins containing polyesters based on
			<u> </u>	polyalkylene stycols
4,963,636	10/16/90	07/479,223	02/12/90	Adhesion promoters
4.977.214	12/11/90	07/420,193	10/12/89	Curable enoxide resin compositions
4.997.951	03/05/91	07/490.815	03/08/90	imidazoline compounds
5.021.513	06/04/91	07/592,720	10/04/90	Curable enoxide resin compositions
5.030.698	07/09/91	07/471.574	01/29/90	Composition of epoxy resin, butadiene-acrylonitrile
4		{	l	copolymer and segmented copolyester. copolyanide
6 1 40 040	08/18/92	97/481.424	02/16/90	or copolvesteramide
5,140,069	<u><u><u>v</u></u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u>v</u><u></u></u>	N21401444	9.47.19/20	Tough Epoxy casting resins based on polybutadiene- polyoxyalklenegiycol copolymers
5,152,862	10/06/92	07/628.735	12/17/90	Imidazoline compounds
5,171,769	12/15/92	07/684,550	04/11/91	Filled thixotropic resin compositions composing toox
2.11.1.643	Terrate.	VIIVOSIAL		resin Curing agent, sugar-aldehyde and filler
5,198,065	03/30/93	07/660.510	02/25/91	Method for bonding steel to wood using an epoxy
XIII XXXXXXX	JALLEY IL		ZALE ALE L	primer and adhesive
5,202,390	04/13/93	07/766.883	09/26/91	Butadiene/polar comonomer copolymer and arorhatic
2/1.2.10.2.1.2		Line Charleng.	Sector State C	reactive end group-containing prepolymer
5,230,986	07/27/93	07/649,100	02/01/91	Photosensitive Compositions containing
				benzospiropyrans and uses thereof
5.237.036	08/17/93	07/875,880	04/29/92	Polyol components for the production of polyure han
				mouldings
5,274,054	12/28/93	07/861,705	04/01/92	Adducts of epoxides and amines
5.278,257	01/11/94	07/823.513	01/21/92	Phenol-terminated polyurethane or polyurea/urethane
L	}			with epoxy resin
5,340,900	08/23/94	08/096,136	07/22/93	Hardener composition for the production of
				polyurethane shaped articles
5.342.867	08/30/94	08/129.703	09/30/93	Adhesion Promoters
5,437.964	08/01/95	08/201.146	02/24/94	Stereolithography using vinyl ether-epoxide polymers
5,449,704	09/12/95	08/166.763	12/14/93	Photopolymerisable liquid compositions comprising
		1		resol and aminotriazine resins
5.451,345	09/19/95	08/129.701	09/30/93	Chemical composition
5,451,616	09/19/95	08/284.729	08/02/94	Photopolymerisable liquid compositions for forming
			1	heat curable solid film adhesives
5,461,088	10/24/95	08/292.654	08/18/94	Liquid radiation-curable formulation, in particulat for
				use in stereolithography
5,468,886	11/21/95	08/169.938	12/20/93	(Cyclotaliphatic epoxy compounds
5.470.689	11/28/95	08/200.982	02/24/94	Polymerisable compositions containing tetraacrylates
5.476,748	12/19/95	08/166.767	12/14/93	Photosensitive composition
5,476,749	12/19/95	08/303,563	09/09/94	Photosensitive compositions based on acrylates
5,487,966	01/30/96	08/231.953	04/21/94	Photosensitive composition
		- Salad Lindala		A THE REPORT OF THE PARTY AND A THE PARTY AND

PAGE 16/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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	5.494.618	02/27/96.	08/266.829	06/27/94	Increasing the useful range of cationic photoinitiators
	5,495,029	02/27/96	08/286.061	08/04/94	in stereolithography (Meth)acrylates containing urethane groups
ł	5.506.087	04/09/96	08/231,353	04/20/94	Stereolithography using vinvi ether based polymers
	5.510.226	04/23/96	08/230,444	04/20/94	Stereolithography using vinvi ether-epoxide polymers
ł	5,514,519	05/07/96	08/224.503	04/07/94	Production of three-dimensional objects
ł	5,525,400	06/13/96	07/783.701	05/10/91	Information carrier and process for the production
					thereof
	5.573.889	11/12/96	08/432.237	05/09/95	Process for adjusting the sensitivity to radiation of photopolymerizable compositions
	5,599,651	02/04/97	<u>Q8/517,888</u>	08/21/95	(Cyclo)aliphatic epoxy compounds
	5.605.941	<u>92/25/97</u>	Q8/3Q4.464	09/12/94	Vinyl ether compounds having additional functional groups other than vinyl ether groups and the use thereof in the formulation of curable compositions
	5,620,553	Q4/15/97	08/443.949	05/28/95	Photopolymerisable liquid compositions of bonding friction material to metal
	5.629.133	05/13/97	08/449.172	05/24/95	Liquid radiation-curable formulation in particular for use in stereolithography
2,60	5.645.973	07/08/97	08/592.899	01/29/96	Process for adjusting the sensitivity to radiation o photopolymerizable compositions
·	5.658.712	08/19/97	08/552,643	11/03/95	(Meth)acrylates containing urethane groups
	5.677.107	10/14/97	08/643,790	05/06/96	Production of three-dimensional objects
	5.705.116	01/06/98	08/463.086	06/21/95	Increasing the useful range of cationic photoiniliators in stereolithography
-	5.705.316	01/06/98	08/555.821	11/09/95	Vinvl ether compounds having additional functional groups other than vinvl ether groups and the use thereof in the formulation of curable composition
	5.708.120	01/13/98	08/586,840	01/25/96	Gelled reactive resin composition
	5,783,358	07/21/98	08/611.914	03/06/96	Stabilization of liquid radiation-curable compositions
					against undesized premature polymerization
	5.783.615	07/21/98	06/834.404	Q4/16/97	Yinyl ether compounds having additional functional groups other than vinyl ether groups and the use thereof in the formulation of curable compositions
	5.783.712	07/21/98	<u> 08/689.747</u>	08/13/96	Vinyl ether compounds having additional functional groups other than vinyl ether groups and the use thereof in the formulation of curable compositions
	<u>5.859.096</u>	Q1/12/99	08/820,822	<u>03/19/97</u>	Room temperature storage stable, heat-curable, ldw CIE, one component epoxy resin tooling materia
	5,897.028	04/27/99	08/377.720	01/24/95	Two component adhesive dispensing unit
	5,908,901	06/01/99	08/944.672	10/07/97	Gelled reactive resin compositions
	<u>5,942,182</u>	08/24/99	<u>08/999,527</u>	09/19/97	One component room temperature stable epoxy resin compositions for VARTM/RTM systems
	5.942.370	08/24/99	08/893.835	07/11/92	Production of three-dimensional objects
	5,972,563	10/26/99	08/901.303	07/28/97	Liquid radiation-curable composition, especially or stereolithography
315	<u>5.989.475</u>	11/23/99	09/091,452	06/18/98	Process for the stereolithographic preparation of bree- dimensional objects using a radiation-curable lightid formulation which contains fillers
7 '	6.043.323	03/28/00	08/342.955	11/21/94	Diarylates and dimethacrylates
	6,057,389	05/02/00	09/022.754	02/12/98	Curable Compositions
	6.060.544	05/09/00	09/040.989	03/18/98	Chemical compositions
	6,077,886	06/20/00	08/947,997	10/09/97	Curable Resin Compositions
	6,086,795	07/11/00	09/181,163	10/28/98	Adhesive Compositions
	6.099.787	06/08/00	09/115.086	07/14/98	Process for making three-dimensional articles by stereolithography
	6.100.007	08/08/00	09/055.832	04/06/98	Liquid, radiation-curable composition, especially for producing cured articles by stereolithography having high heat deflection temperatures
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PAGE 17/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

### TERMINATION OF SECURITY INTEREST (Patents)

This **TERMINATION OF SECURITY INTEREST**, dated as of December 20, 2005, is made by Deutsche Bank AG New York Branch, as Agent (the "<u>Agent</u>").

WHEREAS, Vantico Inc. and Vantico A&T US Inc. (now known as Huntsman Advanced Materials Americas Inc.) (the "<u>Grantor</u>"), with its principal offices at 4917 Dawn Avenue, East Lansing, MI 48823, has granted to the Agent a security interest in certain personal property, including without limitation a security interest in certain patent applications listed on <u>Exhibit A</u> hereto ("<u>Patents</u>"); and

WHEREAS, the Agent has agreed to terminate and release its security interest in all of such Patents as herein provided;

NOW, THEREFORE, for valuable consideration, the Agent hereby terminates and releases all mortgages, liens and security interests granted to the Agent in Grantor's Patents referred to on Schedule A hereto.

### [SIGNATURE PAGE FOLLOWS]

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PAGE 18/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston Strawn * DURATION (mm-ss):18-38

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IN WITNESS WHEREOF, the Agent has caused this Termination of Security Interest to be duly executed as of the date first set forth above.

> DEUTSCHE BANK AG NEW YORK BRANCH, as Agent

Name: Title: Auson Lefeure By: By: Name: Susan LeFevre Title:

Director

Signature Page to Termination of Security Interest

PAGE 19/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

STATE OF KENTORE ) SS COUNTY OF KENTORK )

On this 16 day of December, 2005 before me personally came MARTKAY COYLE, to me known, who, being by me duly sworn, did depose and say that (s)he is MANAGING MEETER of DEUTSCHE BANK, the entity described in and which executed the foregoing instrument; and that (s)he signed his/her name thereto was authorized to execute such instrument.

Notary Public JOJEANTRAVIS Registration No. 01TR5013241 New York County July 15, 200-

STATE OI ) \$\$ ENTORK; COUNTY OF (

On this  $\frac{16}{16}$  day of December, 2005 before me personally came  $\frac{MSAN(EFC)/kto}{EFC}$  me known, who, being by me duly sworn, did depose and say that (s)he is  $\frac{MSAN(EFC)/kto}{EFC}$  of  $\frac{MSAN(C)}{EFC}$ , the entity described in and which executed the foregoing instrument; and that (s)he signed his/her name thereto was authorized to execute such instrument.

Notary Public

Registration No. 01TR5019241 New York County July 15, 20057

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PAGE 20/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

SCHEDULE A

### SCHEDULE OF PATENT APPLICATIONS

See Attached

- 4 -

PAGE 21/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

All patents are encumbered with security interests.

U.S. PATENT APPLICATIONS

Application	Filed	Title
08/268,094	06/28/94	Epoxy acrylates
08/589,435	01/22/96	Curable epoxy resin formulation
08/876,550	06/16/97	Preparation of mouldings by the automatic pressure
		gelation technique using a one component
		composition
09/002,847	01/05/98	Curable epoxy resin composition comprising fillers
09/787,220	03/16/01	Method for producing etched circuits
09/787,221	03/16/01	Method for producing multi-layer circuits
09/856,116	05/17/01	Crosslinking agent for carboxyf-containing polymers
		in heat-curable systems
09/857,684	06/07/01	Hydrophobic epoxide resin system
09/868,817	06/21/01	Production of photoresist coatings
09/890,213	07/26/01	Melamine-modified phyllosilicates
09/932,731	08/17/01	Epoxy acrylates
09/936,706	09/14/01	Hardenable composition with a particular combination
		of characteristics
09/937,001	09/19/01	Matting agents for thermally curable systems
10/019,910	11/09/01	Photosensitive composition
10/031,108	01/10/02	Nanocomposites
10/031,134	01/14/02	Filler mixtures
10/031,135	03/29/02	Curable composition
10/031,983	01/25/02	Amine hardener for epoxy resins
10/208,460	07/30/02	Powder coating carboxyl polyester or (poly)
		methacrylate and cycloaliphatic polyepoxide
10/416,978	05/15/03	Positive type photosensitive epoxy resin composition
		and printed-circuit board using the same
10/433,137	05/29/03	Filled epoxy resin system having high mechanical
L		strength values

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PAGE 22/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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#### U.S. PATENTS ISSUED

Patent	Granted	Application	Filed	Title
RE32,745	09/06/88	07/021,151	03/03/87	Polymeric resins derived from 1-oxa-3-aza
			ţ	tetraline group-containing compounds and
			· · · · · · · · · · · · · · · · · · ·	cycloaliphatic epoxides
4,474,929	10/02/84	06/538,033	09/30/83	Polyglycidyl ethers of branched novolacs
4,528,359	07/09/85	06/610,896	05/16/84	Adducts of epoxy resins and amino-substituted
4,540,769	09/10/85	06/654,342	09/25/84	aromatic sulfonic acid amides
4,541,894	09/17/85	06/614,760	05/29/84	Preparation of n-glycidyl compounds Metallizable essentially isotropic polymeric
רעעודעקי	0,11/02	001014/700	03125107	substrates well adopted for printed circuits
4,544,623	10/01/85	06/573.098	01/23/84	Photosensitive coating composition and the
				use thereof for protective purposes
4,594,291	06/10/86	06/716,279	03/25/85	Curable, partially advanced epoxy resins
	00100100			
4,604,317	08/05/86	06/737,591	05/24/85	Curable compositions containing a
4,604,452	08/15/86	06/789.678	10/21/85	polyepoxide and a halogenated bisphenol Metal carboxylate/alkylphenol curing catalyst
31001132	00/15/00	00//09/0/0	10/21/05	for polycyanate esters of polyhydric phenois
4,607,091	08/19/86	06/774,433	09/10/85	Polymeric resins derived from 1-oxa-3-aza
				tetraline group-containing compounds and
·····				cycloaliphatic epoxides
4,608,300	08/26/86	06/619,751	06/11/84	Fibre composite materials impregnated with a
	A 10 5 10 5			curable epoxide resin matrix
4,608,434	08/26/86	06/789,679	10/21/85	Metal carboxylate/alcohol curing catalyst for
4,614,674	09/30/86	06/730,121	05/03/85	polycyanate ester of polyhydric phenol Powder coating compositions for the
-,0,-,0,-	03/30/00	00730,121	03/03/05	preparation of malt coatings
4,621,159	11/04/86	06/773,685	09/09/85	Brominated hydroxy aromatic compounds
4,624,912	11/25/86	06/698,952	02/06/85	Thermally transferable layers of radiation
	•			sensitive epoxy resins used to prepare
				protective coatings and relief images
4,632,900	12/30/86	06/708,998	03/07/85	Process for the production of images after
				electrodeposition of positive photoresist on
4,654,447	03/31/87	06/831,400	02/20/86	electrically conductive surface Process for the preparation of
	03171707	00/03/,400	02/20/00	tribromotetramethylbiphenol and related
				compounds
4,656,292	04/07/87	06/745,748	06/17/85	2,3-dimethylmaleimido-alkyl haloacetates
4,661,578	04/28/87	06/801,360	11/25/85	High temperature epoxy resin composition
				with reduced viscosity
4,661,644	04/28/87	06/812,476	12/23/85	Brominated Epoxy Aromatic compounds
4,666,954	05/19/87	06/642,909	08/21/84	Process for the preparation of prepregs, and
			1	the reinforced composite materials which can
4,666,997	05/16/87	06/773,724	09/09/85	be obtained therewith Heat-curable mixture containing substitute
4,000,007	05/10/07	00///3,/24	05/05/05	bicyclo(2.2.1.)Hept-5-ene-2, 3-dicarboximide
				and polymaleimide, and the use thereof
4,668,718	05/26/87	06/780,160	09/26/85	Self-extinguishing, track-resistant epoxy resin
	•			moulding composition and use thereof
4,668,807	05/26/87	06/807,566	12/11/85	Process for reducing the content of
I				hydrolyzable chlorine in glycidyl compounds
4,672,103	06/09/87	06/829.361	02/14/86	Non-sintering epoxy resins prepared from
				triglycidyl ethers and epihalohydrins
4,681,923	07/21/87.	06/831,685	02/21/86	Modified quinone-diazine group-containing
4 6 9 4 700	09/04/07	00/020 2/	0.010.000	phenolic novolak resins
4,684,700	08/04/87	06/829,364	02/14/86	Advanced epoxy resins prepared from
L	I	<u> </u>	L	triglycidyl ethers and dihydric phenols

PAGE 23/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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Patent

Granted Application

Title

4,684,752	08/04/87	06/858,473	04/30/86	Di-ortho-substituted di-meta-halogenated para- halomethylphenols
4,689,378	08/25/87	06/809.444	12/16/85	Stable imide-containing composition from
,				diamino phenyl indane-bis-malelmide and
1 1	ł			alkenyl phenol
4,709,008	11/24/87	06/880,529	06/30/86	Blend of tris (cyanatophenyl) alkane and
			_	bis(cyanatophenyl) alkane
4,722,983	02/02/88	06/939,213	12/08/86	Process for the preparation of glycidyl
	•			compounds
4,731,423	03/15/80	06/896,480	08/13/86	Meta-halo-phenolic alkylation products and
				epoxy systems
4,737,553	04/12/88	06/912,722	09/29/86	Advanced resins from diglycidyl ethers of de-
			0.010.010.0	secondary alcohols and dihydric phenols
4,740,584	04/26/88	06/904,610	09/08/86	Blend of dicyanate esters of dihydric phenols
4,742,141	05/03/88	06/929,837	11/13/86	Imido polymer from bis imide and
4,749,767	06/07/88	07/059,366	06/08/87	alkenyloxyaniline Stable imide-containing composition from
4,/49,/0/	00/0//00	077039,300	06/06/07	diaminophenylindane-bis-Imide, amine and
				alkenyl phenol or ether (chaudhari)
4,756,756	07/12/88	06/705.726	02/26/85	Forming of thick-layer, hybrid electronic-
4,7 30,7 30	0//12/00	00//03//20	02/20/05	printed circuits (oassat)
4,785,075	11/15/88	07/078,037	07/27/87	Metal acetylacetonate/alkylphenol curing
1,1 00,01 2				catalyst of polycyanate esters of polyhydric
1			[	phenols (shimp)
4,799,996	01/24/89	07/078,166	07/27/87	Metallizable substrate composites and printed
1				circuits produced therefrom (Cassat)
4,800,215	01/24/89	07/170,217	03/15/88	Compositions prepared from dialkanolamines
ŀ				and triglycidyl ethers of trisphenols (Bertram;
				Myles; Kubisiak)
4,826,927	05/02/89	07/000,255	01/02/87	Mixtures containing polymides alkenyphenois
	[		[	and either epoxide group-free adducts or
4,829,138	05/09/89	07/159,907	02/24/88	another polymide (Schmid) Novel heat-stable siloxane/bismaleimido
4,029,130	03/07/09	0/1139,907	02/24/00	polymers (Barthelemy)
4,839,440	06/13/89	07/134,043	12/17/87	N,N'-bis(malelmide)salkenyloxyanaline
1,033,110				copolymerizates (Barthelemy)
4,839,442	06/13/89	07/210,175	06/20/88	Low viscosity noncrystalline dicyanate ester
				blends with prepolymers of dicyanate esters
		1	1	(Craig)
4,845,172	07/04/89	07/186,753	04/26/88	Co-advanced resins from copolymers of
1	1 .	Į	Į	polyethers of polyhydric phenols and
			{	diglycidyl ethers of di-secondary alcohols
	· · · · · · · · · · · · · · · · · · ·	4	L	(Brytus)
4,847,233	04/11/89	07/228,469	08/05/88	Metal acetylacetonate/alkylphenol curing
1	1	1	1	catalyst for polycyanate esters of polyhydric
				phenols (Shimp)
4,847,343	07/11/89	07/166,501	03/10/88	Heat-resistant maleimido copolymers
4,847,344	07/11/89	07/166,482	03/10/88	Novel heat-resistant maleimido copolymers
4,848,533	07/18/89	07/243,181	09/14/88	Apparatus for conveying panels (Martin)
4,849,320	07/18/89	07/045,022	04/30/87	Method of forming images (Irving)
4,849,490	07/18/89	07/159,911	02/24//	Novel bis(Maleimide)/polysiloxanes
4,857,607	08/15/89	07/195,312	05/18/88	Epoxidized polycycloacetals (Cotting)
4,861,438	08/29/89	07/297,372	01/17/89	Method of making patterns (Banks)
4,885,354	12/05/89	07/258,542	10/17/88	Epoxy resin compositions (Hofer)
4,892,925	01/09/90	07/300,460	01/23/89	Process for preparing phenolic hydroxyl-
			4	containing compounds from 2,6-Dibromo-3,5-
		07/26/200	1 100 100	dialkyl-4-hydroxybenzyl ethers
4,895,755	01/23/90	07/259,449	10/14/88	Halogenated Advanced Epoxy resins

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PAGE 24/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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Γ	4,914,185	04/03/90.	06/851,996	04/14/86	Adducts of metabrominated phenols and
					polyfunctional epoxides (Wang et al.)
ſ	4,923,520	05/08/90	07/251,995	09/30/88	Spherical fused silica and its use in fillers and
					resin compositions (Anzai & Hamabe)
- X [	4,926,789	05/22/90	07/252,302	10/03/88	Transport apparatus for boards (Wenger)
	4,931,545	06/05/90	07/347,251	05/03/89	Flame retardant polycyanate ester blend
ŀ	4,940,848	07/10/00	07/269,862	11/10/88	(Shimp)
	4,940,040	07/10/90	0//209,002	11/10/68	Stable solutions f prepolymers of thiodi(phenylcyanate) and laminating method
					employing same (Shimp)
1	4,950,728	08/21/90	202,544	06/06/88	Thermally stable (imide/amide)(urea/siloxane)
					block copolymers
	4,957,946	09/18/90	07/202,739	06/03/88	Cationically polymerizable mixtures
		· · ·			containing metallocene complex salt of certain
					carboxylic or sulfonic acids (Meier)
1	4,962,178	10/09/90,	07/266,555	11/03/88	Novel polysiloxane - polyurethanes and
	4,963,300	10/16/90	07/279,747	12/05/88	contact lens thereof
ŀ	4,973,648	11/27/90	07/411,949	09/25/89	Process for the preparation of laminates Epoxy resin compositions (Hofer)
	4,973,649	11/27/90	07/319,306	03/03/89	Hindered diamine/imido prepolymers
	4,975,500	12/04/90	07/440,149	11/22/89	Adducts of metabrominated phenols and
					polyfunctional epoxides
୍ର ପତ୍ର	4,978,604	12/18/90	07/208,524	06/20/88	Process for forming images (Banks)
· · ·	4,978,809	12/18/90	07/434,150	11/13/89	Meta-halogenated dibenzylphenols
	4,992,488	02/12/91	07/403,845	09/01/89	Glass fibre-reinforced epoxide resin moulding
	( 000 ( 70				composition and its use (Ruf)
1	4,992,572	02/12/93	07/258,544	10/17/88	Process for the preparation of organometallic
	4,994,346	02/19/91	07/221,846	07/20/88	compounds (Desobry) Negative photoresist based on polyphenols
	-,,,,,,,,,,	02/13/31	0/1221/040	07720708	and selected epoxy or vinyl ether compounds
				-	(Meier)
	4,996,285	02/26/91	07/420,723	10/11/89	Imide/epoxy thermosetting compositions
					(Arpin)
	5,002,858	03/26/91	07/434,599	11/07/89	Process for the formation of an image
	E 004 424	04/00/01		00/05/00	(Demmer)
	5,006,626 5,013,804	04/09/91 05/07/91	07/411,951 07/505,097	09/25/89	Epoxy resin compositions (Hofer)
	5,015,004	05/0//91	07/505,097	04/03/90	Curable mixtures containing a bismaleimide and a propenyl compound (Kramer)
	5,013,814	05/07/91	07/462,252	01/09/90	Araliphatic sulfonium salts and their use (Roth)
100	5,019,639	05/28/91	07/503,399	04/02/90	Novel epoxy resins (Hofer)
``	5,021,484	06/04/91	07/376,875	07/07/89	Fire retardant curable 1-oxa-3-aza tetraline
		•			(also termed "3.4-dihydro-1,3-benzoxazine")
					derived resin composition
		0.7/2			(Schreiber)
	5,028,668	07/02/91	07/549,177	07/06/90	Adducts of metabrominated phenols and
	5,030,730	07/09/91.	07/493 140	02/21/90	polyfunctional epoxides
	5,030,730	07/23/91 •	07/483,149 07/598,126	10/16/90	Curable mixtures (Munk)
	5,034,303	08/06/91	07/544,061	06/26/90	Novel imido copolymers (Camberlin) Novel imido Polymers
	3,037,723		100,44,001	00/20/90	(R. Arpin)
	5,053,474	10/01/91	07/426,850	10/26/89	Imido polymers (Camberlin)
	5,068,309	11/26/91	07/501,231	03/29/90	Low temperature curable dicyanate ester of
	1		471001/201	1	dihydric phenol composition (Shimp)
	5,073,233	12/17/91	07/532,533	06/04/90	Method of making a metallic pattern on a
		•		1	substrate (Banks)
		1			
	5,073,478	12/17/91	07/439,724	11/20/89	Method of making a pattern (Banks)
	L	L	L	1	-



PAGE 25/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston Strawn * DURATION (mm-ss):18-38

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	5,079,129	01/07/92	07/445,134	11/30/89	Negative photoresist based on polyphenois and epoxy compounds or vinyl ethers (Roth))
	5,080,998	01/14/92	07/629,099	12/17/90	Process for the formation of positive images utilizing electrodeposition of o-quinone
					diazide compound containing photoresist on conductive surface (irving)
	5,082,952	01/21/92	06/867,113	05/27/86	Process for the preparation of metallocene complexes (Meler)
	5,086,154	02/04/92	07/550,047	07/09/90	Linear aromatic poly/amideimide)s having latent maleimide end groups (Camberlin)
	5,087,688	02/11/92	07/541,237	06/20/90	Fibrous composite structure impregnated with a solvent-free curable epoxy resin matrix (Cruber)
	5,098,527	03/24/92	07/408,860	09/18/89	Method of making electrically conductive patterns (Banks)
	5,098,963	03/24/92	07/652,845	02/08/91	Adducts of metabrominated phenols and polyfunctional epoxides (Wang, Mendoza)
	5,112,440	05/12/92	07/601,162	10/22/90	Method for making metallic patterns (Banks)
	5,113,701	05/19/92	07/647,322	01/29/91	Transport device for boards having a sensitive surface especially for wet-coated circuit boards (Martin)
	5,113,785	05/19/92	07/590,902	10/01/90	Transport device for boards, especially those having a sensitive surface (Martin)
120	5,115,005	05/19/92	07/756,405	09/09/91	Phosphinic acid flame retardant (Horner)
IC 1	5,117,010	05/26/92	07/745,569	08/15/91	Process for the preparation of addition products of epoxides and alcohols (Cheng)
	5,122,589	06/16/92	07/506,743	04/10/90	Imido/siloxane bismaleimide/aroma(ic diamine prepolymers (Cambertin)
	5,122,590	06/16/92	07/506,744	04/10/90	Imido/hindered diamine copolymers (Camberlin)
	5,124,233	06/23/92	07/202,765	06/03/88	Photoresist composition
	5,124,419	06/23/92	07/696,706	05/07/91	Imido polymers (R. Arpin)
	5,128,491	07/07/92	07/738,072	07/30/91	Process for the Preparation of Glycidyl Ethers of Di-secondary Alcohols with High Monomer Content
	5,130,406	07/14/92	07/496,557	03/19/90	Initiators for Materials which can be polymerized Cationically
	5,130,452	07/14/92	07/695,856	05/06/91	Phosphorus compounds and their use a flame retardant for polymers
	\$,132,346 _.	07/21/92	07/741,389	08/07/91	Fame retardant compositions of halogen-free polymers containing cyclic phosphate or thiophosphate flame retardants
	5,136,110.	08/04/92	07/626,597	12/12/90	Process for the preparation of bisphenols (Walters, Richey, Tasset)
	5,149,767	09/22/92	07/595,918	10/11/90	Thermosetting mixtures utilizing araliphatic sulfonium salts.
	5,149,841.	09/22/92	07/694,525	05/01/91	N,N,N',N'-tetracycidyl-4,4,'- diaminodiphenylmethanes
	5,149,863	09/22/92	07/744,065	08/12/91	Low temperature curable dicyanate esters of dihydric phenols
	5,153,101.	10/06/92	07/537,394	06/13/90	Photoresist
	5,162,574	11/10/92	07/581,778	09/13/90	Bix(4-cyanalophenyl)-1, 1-ethang
	5,179,179	01/12/93	07/874,782	04/27/92	Initiators for materials which can be polymerized cationically
ĺ	5,183,869	02/02/93	07/699,541	05/14/91	Hardenable compositions

PAGE 26/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR: USPTO-EFXRF-6/24 * DNIS: 2709907 * CSID: Winston Strawn * DURATION (mm-ss): 18-38

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07/16/91 5,198,516 03/30/93 07/730,537 Thermally stable bisimido/P-allylaniline copolymers 5.200.452 04/06/93 07/791.817 11/18/91 Fire retardant curable 1-oxa-3-azatetraline (also termed "3,4-dihydro-1,3-benzoxazine") derived resin composition N,N*-bis(maleimide)/hindered diamine 04/27/93 07/790.023 11/05/91 5,206,338 ٠., copolymerizate 5,208,110 05/04/93 07/368,452 06/19/89 Security cards 06/22/93 07/864,146 04/06/92 Thermally stable bisimido copolymerizates 5,221,723 07/20/93 07/766,467 09/26/91 5,229,485 Soluble polyimides Curtain coaling process for producing thin photoimageable coalings 08/17/93 07/908,604 06/29/92 5,236,746 5.239.093 08/24/93 07/930,114 08/14/92 Process for the preparation of addition products of epoxides and alcohols Flame retardant polyimide system Production of glycidyl compounds Araliphatic sulfonium and their use 5,240,981 08/31/93 07/709,905 06/03/91 12/11/91 5,245,048 09/14/93 07/805,430 01/07/91 5,247,113 09/21/93 07/638,602 5,262,501 11/16/93 07/881,587 05/12/92 Mixtures of spiroheptadienes Ø 5,272,227 12/21/93 07/747,594 08/20/91 Adducts of hydroxyl-group containing epoxy reins and isocyariates and use thereof 01/18/94 07/693,874 04/30/91 N-glycidyl compound 5,280,069 07/769,356 09/30/91 5,284,968 02/08/94 Process for preparing bis (4-cyanatophenyl)-1-ethane 02/15/94 07/916,933 07/20/92 Photoresist 5,286,611 03/01/94 07/872,745 04/22/92 Heat-conductive adhesive films, laminates 5.290.624 with heat-conductive adhesive layers and the use thereof Solid compositions of polyglycidyl compounds having a molecular weight of less 5,294,683 03/15/94 07/952,123 09/28/92 than 1500 Thermocurable compositions 5,296,567 03/22/94 07/863,638 04/06/92 04/05/94 07/947,899 09/17/92 Process for the production of relief structures 5,300,380 using a negative photoresist based on polyphenols and epoxy compounds or vinyl ethers. (Roth, Meier) Polyglycidyl compounds (Michael R. Thoseby; 5,304,662 04/19/94 08/000,900 01/06/93 Bryan Dobinson 06/14/94 08/131,272 10/04/93 5,321,103 Compositions comprising aminoplast resins and solid colloidal condensation polymers (Alfred Renner) 1.0 Hardeners for powder coating compositions based on polyester resins (Cotting; Gottis) 5,322,907 06/21/97 07/856,240 03/25/92 07/19/94 08/19/93 5,331,068 08/109,415 Adducts of diaminodiphenyl sulfone compounds as hardeners for epoxy resins 5,332,781 07/26/94 08/080,797 06/22/93 Storage-stable suspension of tougheners in epoxy resin hardeners 5,339,537 08/23/94 07/973,469 11/09/92 Continuous drier for flat piece material 5.342.903 08/30/94 08/055,656 04/30/93 Process for the Preparation of adducts of epoxides and alcohols 5,344,635 09/06/94 08/011,930 02/01/93 Filler for heat-conductive plastics materials 5,352,831 10/04/94 07/914,158 07/14/92 Oligomeric cyanoguanidines 5.359.020 10/25/94 07/701,264 05/16/91 Hardenable compositions comprising bismaleimides alkenylphenols and phenol diallyl ethers 5,362,835 Production of compounds 11/08/94 07/804,308 12/09/91 5,362,849 08/147,705 11/04/93 N-Glycidyl compound 11/08/94

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PAGE 27/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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	5,366,947	11/22/94	07/931,755	08/18/92	Initiators for materials which can be polymerized cationically
	5,371,115	12/06/94	07/870,156	04/15/92	Cationically polymerizable compositions containing iron metallolene salt
	5,371,259	12/06/94	08/046,350	04/08/93	Iron (II) metallocene salis
	5,374.697	12/20/94	08/091,803	07/14/93	Selected novel sulfonium compounds particularly suitable as initiators for the thermal cure of cationically polymerisable materials
	5.382.710	01/17/95	07/922,450	07/30/92	Aromatic polyhydroxy compounds and process for the preparation thereof (Walters, Richey, Tasset)
	5,391,681	02/21/95	08/068,376	05/27/93	Curable compositions based on epoxy resins or mixtures of epoxy resins and polyisocyanates containing trisimidazolyl triazines
	5,399,416	03/21/95	08/159,389	11/30/93	Heat-conductive adhesive films, laminates with heat-conductive adhesive layer and the use thereof
	5,403,907	04/04/95	08/104,048	02/14/92	Prepolymers having imide groups
[	5,412,065	05/02/95	08/045,395	04/09/93	Polymide oligomers
	5,420,312	05/30/95	07/979,011	11/20/92	Glycidyl ether from alcohol and
,çu	5,420,342	05/30/95	08/154,642	11/19/93	Process for preparing bis (4-cyanatophenyl)- 1,1-ethane
	5,424,373 5,426,150	06/13/95 06/20/95	08/268,091	06/28/94	Oligometic cyanoguanidines hardeners for epoxy resins
	5,420,130	08/22/95	08/241,212	05/10/94	Preparing suspension of epoxy resin hardener and toughener
				11/12/93	Curable resins comprising halogenated epoxy resins and 1-oxa-3-AZA tetraline compounds, method for preparing and use of resins
	5,451,362	09/19/95	08/154,201	11/18/93	Moulding process
	5,457,168	10/10/95	08/384,793	02/13/95	Solid compositions of polyglycidyl compounds having a molecular weight of less than 1500
	5,470,896	11/28/95	08/376,539	01/20/95	Storage-stable solutions of accelerator systems
	5,470,920	11/28/95	08/122,600	04/03/92	Impregnating solutions based on at least one reactive thermoplastic poly (imide – amide) oligomer and a coreactant; which can e used especially for the production of preimpregnated intermediate articles
	5,478,915	12/26/95	08/175,817	12/30/93	Polyimide oligomers
	5,494,944	02/27/96	08/292,658	08/18/94	Hardenable composition and its use
	5,501,942	03/26/96	08/304,643	09/12/94	Photosensitive composition containing water as solvent or dispersant
	5,503,936	04/02/96	08/371,645	01/12/95	N-alkyl-n'-aryl-p-phenylenediamines as modifiers for epoxy resins
	5,505,895	04/09/96	08/166,749	12/14/93	Process for making moulded articles of epoxy resin compositions
	5,506,313	04/09/96	08/301,468	09/07/94	Phosphorus-containing flameproofing agents for epoxy resin materials
	5,512,372	04/30/96	08/256,376	01/13/93	Epoxy resin composition and applications, in particular in composite structures using imidazole/polyamine mixture
	5,521,261	05/28/96	08/250,125	05/27/94	Epoxy resin mixtures containing advancement
	5,523,044	06/04/96	08/259,642	06/14/94	Process for molding epoxy resins with coarse decorative particles

PAGE 28/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston Strawn * DURATION (mm-ss):18-38

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5,523,362	06/04/96	06/412,181	03/28/95	Ofigomeric cyanoguanidines
5,525,685	06/11/96	07/706,683	05/29/91	Epoxy resin compositions
5,541,282	07/30/96	08/336,597	11/09/94	Aromatic polyhydroxy compounds and process for the preparation thereof
5,543,572	08/06/96	08/377,719	01/24/95	Monocarboxamides of polyamines
5,552,459	09/03/96	08/240,791	05/10/94	Highly filled epoxy casting resin composi
5,565,500	10/15/96	08/310,452	09/22/94	Cationically polymerizable mixtures containing selected metallocene complex as curing agents
5,567,237	10/22/96	08/259,641	06/14/94	Continuous drier for board-shaped piece material and coating installation compris such a continuous drier
5,569,734	10/29/96	08/432,112	05/03/95	Curable epoxy resin mixtures containing salts
5,576,399	11/19/96	08/268,095	06/28/94	Epoxy acrylates
5,591,811	01/07/97	08/527,132	09/12/95	1-imidazolylmethyl- 2-naphthols as catalysts for curing epoxy
5,597,886	01/28/97	08/512,044	08/07/95	Heat-curable epoxy resin systems having good reactivity/stability ratio
5,606,013	02/25/97	06/948,278	12/31/86	Polyamic acids and polyimides
5,614,126	03/25/97	08/449, 144	05/24/95	Solventless curable resin composition in particular for the fabrication of prepregs
5,614,606	03/25/97	06/948,279	12/31/86	Polyamic acids and polyimides
5,616,633	04/01/97	08/303,904	09/09/94	Liquid epoxy resin compositions
5,633,341	05/27/97	08/211,297	03/30/94	At room temperature crosslinkable compositions, and methods of their manufacture and use
5,637,148	06/10/97	08/529,467	09/18/95	Apparatus for coating board-shaped piece material on both sides
5,637,387	06/10/97	08/462,438	06/02/95	Storage-stable advanced polymaleimide compositions
5,652,322	07/29/97	08/715,054	09/17/96	Heat-curable epoxy resin systems having good reactivity/stability ratio
5,668,227	09/16/97	08/613,393	03/11/96	Cyclohexyl-group-containing glycidyl et
5,691,006	11/25/97	08/568,092	1 2/06/95	Solder resist coating form photosensitive composition containing water as solvent dispersant
5,703,343	12/30/97	08/545,746	11/01/95	Process and plant for the manufacture of castings from an essentially liquid reactiv medium, and oven for heating an essent liquid medium
5,705,541	01/06/98	08/647,077	05/08/96	High gloss molded articles of curable ep resin composition comprising fillers
5,789,482	08/04/98	07/952,122	09/28/92	Epoxy resin with anhydride, roughener a active hydrogen-containing compound
5,821,318	10/13/98	08/779,181	01/06/97	Hardener composition for epoxy resins
5,844,047	12/01/98	08/838,765	04/10/97	Single component, heat curing composit which are stable when stored at room temperature and which comprise polym containing anhydride groups and powde crosslinking agents, and their method of manufacture and use
5.847.376	12/08/98	08/840,561	04/15/97	Process and plant for the manufacture of castings from an essentially liquid reacti medium, and oven for heating an essent liquid medium
5,872,163.	02/16/99	08/738,561	10/28/96	Liquid epoxy resin composition contain wollastonite and calcite

PAGE 29/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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Г	5,900,204	05/04/99	08/894,544	03/01/96	Production of thermoset pressure gelation
L 1					castings
Ļ	5,904,888	05/18/99	08/973,649	06/18/96	Curable compositions
L	5,906,784	05/25/99	08/959,502	10/28/97	Curable epoxy resin compositions
	5,908,668	06/01/99	08/991,523	12/16/97	Curtain coating apparatus having a planar
					deflector surface and method for using the
ŀ	5,939,242	08/17/99	08/757,391	11/27/96	same Positive Photoresist with an alkoxyalkyl ester
	5,959,242	00/1//39	00//5/,391	11/2//90	group-containing (co)polymer and carboxyl-
					group containing (co)polymer
l l	5,942,371	08/24/99	08/714.633	09/13/96	Aqueous acrylic photopolymerisable
					compositions
	5,955,551	09/21/99	08/907,285	08/06/97	Polyglycidyl ethers of secondary alcohols,
					their preparation, and curable compositions
L L	<u></u>	11/20/20			containing them
	5,994,432	11/30/99	07/727,539	07/09/91	Storage-stable/clear solutions of
ŀ	5,994,475	11/30/99	08/886,308	07/01/97	poly(imideamides) Reaction products of amine and a carboxyl
	JIJFFE	11130133	001000,300	0//0//3/	functional microgel
. r	6,001,428	12/14/99	08/630,738	04/10/96	Solid epoxy resin compositions crosslinkable
					with UV rays
Г	6,001,902	12/14/99	09/048,821	03/26/98	Wollastonite-containing curable epoxy resin
-		· · · · · · · · · · · · · · · · · · ·			mixture
	6,029,944	02/29/00	08/894,451	02/24/96	Casting device and an adapter for a casting
-	6 020 311	02/20/00	00/10/ 537	11/00/00	device
	6,030,713	02/29/00	08/184,537	11/02/98	Electrical or Electronic Components Encapsulated with Liquid Epoxy Resins
					Containing a Mixture of Wollastonite and
					Calcite Fillers
	6,037,392	03/14/00	08/755,382	11/21/96	Core/shell particles, and curable epoxy resin
					composition
	6,045,972	04/04/00	09/320,919	05/27/99	Coating method using aqueous
f f	6.040.046	04/11/00	00/13737	00/20/20	photopolymerizable compositions
ŀ	6,048,946 6,054,536	04/11/00	09/137,371 09/124,139	08/20/98	Hydrophobic epoxy resin systems
ŀ	6,066,435	05/23/00	09/075,638	05/11/98	Epoxy resin compositions Liquid photosensitive composition
ŀ	6,090,891	07/18/00	09/075,639	05/11/98	Carboxyl-containing polymer(s) with (2-oxo-
	0,000,000	0//10/00	09/07 32033	05711730	1,3-dioxolan-4-yl)methyl groups-containing
· · · •		[			compound(s)
	6,093,493	07/25/00	09/100,003	06/17/98	Method for the coating or encapsulation of
					fluidizable substrates
	6,103,157	0815/00	09/100,005	06/17/98	Process for impregnating electrical coils, and
					selected epoxy resin composition for carrying
-	6,103,825	08/15/00	09/070.662	04/30/98	out the impregnation
1	0,103,025	00/15/00	09/0/0,002	04/30/98	Epoxy resin pre-advanced with carboxyl- containing polyester and advanced with
1					bisphenol
ł	6,107,451	08/22/00	09/177,141	10/21/98	Hardener for anhydride group-containing
	0,107,131	001200	0.0,1,1,1,1,1	10/21/30	polymers
1	6,111,015	08/29/00	08/391,329	02/21/95	Core/shell polymer toughener suspended in
					epoxy resin
[	6,112,885	09/05/00	09/035,310	03/05/98	Transport apparatus for thin, board-shaped
				<u> </u>	substrates
350	6,117,932	09/12/00	09/019,636	02/06/98	Powder coating composition
v ≤	6,132,641	10/17/00	09/077,484	05/29/98	Composition and support material comprising
ļ		10/24/20	0.046.00 0.55		poly(9,9'-spiro-bisfluorenes)
	6,136,922	10/24/00	08/690,373	07/26/96	Composition of carboxyl-containing
1			F	1	poly(meth)acrylate, carboxyl-terminated
1			<u>i</u>	J	polyester and epoxy resin

PAGE 30/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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ſ	6,165,558	12/26/00	09/101,789	07/16/98	Storage-stable moulding powder based on
ŀ	C 160 150	01/02/01	000000000	04/23/99	epoxy resins Polyglycidyl compounds
•	6,169,158 6,174,985	01/16/01	09/298,573	01/25/99	Epoxy resins with n-esters substituted
1	0,1/4,903	01/10/01	09/230/410	01/25/99	imidazoles
ł	6,180,009	01/30/01	09/101,095	02/23/98	Method of filtering the organic solutions
					arising in the production of circuit boards
l l	6,180,693	01/30/01	09/390,122	09/03/99	Core/shell particles, and curable epoxy resin
ł	6,194,490	02/27/01	09/253.162	02/19/99	compositions comprising same Curable composition comprising epoxidised
1	0,194,490	04142101	031233,102	92/13/33	natural oils
Ī	6,197,849	03/06/01	09/248,649	02/11/99	Organophilic phyllosilicates
[	6,197,861	03/06/01	09/230,395	01/27/99	Stabilisation of paints with spiroindane
ļ	6,242,638	06/05/01	09/267,585	03/12/99	derivatives
	0,242,030	00/05/01	09/207,385	03/12/93	Cyanate esters having flame resistant properties
					(CIP filed 06/26/00 - 6,365,671)
Ĩ	6,258,919	07/10/01	09/142,269	09/03/98	Curable epoxy resin compositions containing
ļ		A #14 #104			water-processable polyamide hardeners
1	6,262,148	07/17/01	09/334,085	06/16/99	Novel phenalkamine curing agents and epoxy resin compositions containing the same
ł	6,265,487	07/24/01	09/016.619	01/30/98	Powder coaling of carboxyl-containing
1					poly(meth) acrylic resin and
					trans(cis)diglycidyl 1,4-
1	6,271,463	08/07/01	09/327,859	06/18/99	Use of expandable epoxy systems for barrier materials in high voltage liquid-filled
					transformers
1	6,274,673	08/14/01	09/376,797	08/18/99	Powder coating composition of epoxy resin
1		00/000			mixture and carboxyl-containing
	6,277,929	08/21/01	09/380,449	03/07/97	Polymerizable Unsaturated Compounds, Curable Resin Compositions Containing the
1					same, and Products of Curing thereof
	6,350,825	02/26/02	09/605,193	06/28/00	Reacting Diglycidyl, Bisphenol and
					monophenol with Catalyst and Mixing with
	6,365,671	04/02/02	09/603,504	06/26/00	Polyglycidyl Compositions cyanate ester and aromatic
	0,505,071	UNIVERUE	P00,000,000	00/20/00	compounds having improved heat release
				1	properties
270	6,380,445	04/30/02	09/567,348	05/09/00	Poly(9,9'-spirobisfluorenes), their production
2 I V	6 100 277	06/04/02	09/214,053	12/28/98	and their use Photopolymerizable thermosetting resin
	6,399,277	00/04/02	09/214,055	12/20/90	composition
	6,417,316	07/09/02	09/421,166	10/19/99	Curable epoxy resin compositions
	6,433,084	08/13/02	09/298,572	04/23/99	Powder coating
j	6,437,045	08/20/02	09/697,331	10/25/00	Powder coating of carboxyl polyester or (poly)
			00/700 000	1 2 1 4 1 2 2	methacrylate and cycloaliphatic polyepoxide
	6,455,662	09/24/02	09/728,991	12/4/00	Curable mixtures based on epoxy resins comprising imidazoles
	6,458,993	10/01/02	09/773,305	01/31/01	Cyanate esters having flame resistant
1	0,100,000				properties
	6,465,601	10/15/02	09/787,165	06/15/01	Accelerators for hardenable systems
	6,479,596	11/12/02	08/652,394	05/23/96	Epoxy acrylates
i	6,489,405	12/03/02	08/573,767	12/18/95	Epoxy resin formulation containing epoxy
	( [ ] ] 005	02/11/02	00/710 000	03/12/04	group-terminated polyesters
	6,517,895	02/11/03	09/719,803	03/12/01	Method of coating printed circuit boards or similar substrates
	6,528,594	03/04/03	09/743,501	01/10/01	Flowable granulates
:		1 33/0 11/03			L'encoure descentes

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PAGE 31/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston_Strawn * DURATION (mm-ss):18-38

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Patent	Granted	Application	Filed	Title
6,555,601	04/29/03	09/465,866	12/16/99	Process for impregnating electrical coils, and selected epoxy composition for carrying out the impregnation
6,559,277	05/06/03	10/096,926	03/14/02	Poly(9,9'-spirobis(luorenes), their production and their use
6,562,410	05/13/03	09/743,378	01/08/01	Heat curable epoxy compositions
6,562,884	05/13/03	09/936,710	09/14/01	Epoxy resin compositions having a long shell life
6,579,566	06/17/03	08/999,803	05/20/97	One-component epoxy resin system for trickle impregnation and hot dip rolling

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PAGE 32/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston Strawn * DURATION (mm-ss):18-38

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All patents are encumbered with security interests.

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### PATENT APPLICATIONS

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P	alent-Number-		Date Issued Title
	Application	Filed	Title
	<u>09/418,609</u>	10/15/99	Method for filling and reinforcing honeycomb sandwich panels
	<u>09/703,787</u>	11/01/00	Casting resin and process for the fabrication of resin molds
	<u>09/762.908</u>	02/12/01	Pack for two-component product
ļ	09/762,909	02/12/01	Pack for two-component product and method of making it
	09/762,910	02/12/01	Container and packaging method
	09/776.656	02/05/01	Liquid, radiation-curable composition, especially for stereolithography
- 1	09/868,289	06/15/01	Thermosetting poly urethane/urea-forming compositions
1	09/953,250	09/17/01	Photosensitive diacrylate and dimethacrylate compositions
	09/986.815	11/13/01	Amine-modified epoxy resin reacted in presence of latent hardener
- 1	10/002.181	12/05/01	Method of treating an aluminum surface
	10/018,667	12/12/01	Process for the preparation of reaction products of cycloaliphatic epoxides with multifunctional hydroxy compounds
ľ	10/031.134	01/14/02	Filler mixtures
	10/069,164	02/20/02	Bonding of concrete parts
$\sigma \cup$	10/088.564	03/15/02	UV-curable compositions
	10/125,508	04/19/02	Photocurable compositions containing reactive polysiloxane particles
	10/143.907	<u>05/14/02</u>	Liquid, radiation-curable composition, especially for producing cured articles by stereolithography having high heat deflection temperatures
	10/167.436	06/13/02	Liquid radiation-curable composition, especially for producing flexible cured articles by stereolithography
	10/182.412	07/29/02	Epoxy resin composition
	10/225,830	08/21/02	Use of amino resins and catalyzing redox pairs in three dimensional printing applications
	10/258,204	10/18/02	Coherent insert
ļ	10/283,233	10/30/02	Photocurable compositions with phosphite viscosity stabilizers
	10/332,597	01/10/03	High Functional polymers
	10/380.392	03/11/03	Seamless model and method of making a seamless model
	10/399,444	04/15/03	Three-dimensional structured printing
	10/416.101	04/25/03	High functional polymers

PAGE 33/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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### U.S. PATENTS ISSUED

Patent	Issued	Application	Filed	Title	
4.476.292	10/09/84	06/574.823	01/30/84	Castable polyurethane systems	~~~~
4,540,750	09/10/85	06/653.417	09/24/84	Diethyl toluene diamine hardener systems	
4.659.779	04/21/87	06/847.371	04/02/86	Solid solution of amine and polymerized pherol as epoxy resin cure accelerator	ş
4,701,378	10/20/87	06/847,365	04/02/86	Bonding process using curable epoxide resin adhes	siv
4.713.432	12/15/87	07/002.358	01/12/87	Solid solution of amine and polymerized phenol	
4.734.332	03/29/88	07/002.355	01/12/87	Method for effecting adhesion using laminates from	8
4.866.133	09/12/89	07/095.725	09/14/8Z	Solid solutions of polymeric phenols and polyamin as epoxy curing agents	12
4.916.173	04/10/90	07/190.795	05/06/88	Polyurethane syntactic foam modeling stock	
4.920.182	04/24/90	07/279.884	12/05/88	Epoxy resin compositions containing polyester flexibilizer and metallocene complex initiator	••••
4,933,392	06/12/90	07/376.796	07/07/89	Curable eqoxide resin compositions	
4,952.645	08/28/90	07/287.581	12/16/88	Epoxide resins containing polyesters based on polyalkylene glycols	
4,963.636	10/16/90	07/479.223	02/12/90	Adhesion promoters	
4.977.214	12/11/90	07/420,193	10/12/89	Curable epoxide resin compositions	
4,997,951	03/05/91	07/490.815	03/08/90	Imidazofine compounds	
5.021,513	06/04/91	07/592.720	10/04/90	Curable epoxide resin compositions	
5,030,698 ·	07/09/91	07/471.574	01/29/90	Composition of epoxy resin, butadiene-acrylonitri copolymer and segmented copolyester, copolyanti or copolyesteramide	e id
5,140.069	08/18/92	07/481.424	02/16/90	Tough Epoxy casting resins based on polybutadian polyoxyalklenegiycol copolymers	ię
5,152,862	10/06/92	07/628.735	12/17/90	Imidazoline compounds	
5.171.769	12/15/92	07/684.550	04/11/91	Filled thixotropic resin compositions composing a resin curing agent, sugar-aldehyde and filler	p
5,198,065	03/30/93	07/660.510	02/25/91	Method for bonding steel to wood using an epoxy primer and adhesive	
5,202,390	04/13/93	07/766,883	09/26/91	Butadiene/polar comonomer copolymer and arom reactive end group-containing prepolymer	at
5.230.986	<u>07/27/93</u>	<u>07/649,100</u>	02/01/91	Photosensitive Compositions containing benzospiropyrans and uses thereof	
5.237.036	08/17/93	07/875,880	04/29/92	Polyol components for the production of polyuret mouldings	ba
5,274,054	12/28/93	07/861,705	04/01/92	Adducts of epoxides and amines	
<u>5.278.257</u>	<u>01/11/94</u>	07/823.513	01/21/92	Phenol-terminated polyurethane or polyurea(ureth with epoxy resin	1a
5,340,900	08/23/94	08/096,136	0 <u>7/22/93</u>	Hardener composition for the production of polyurethane shaped articles	
5,342,867	08/30/94	08/129.703	<u>09/30/93</u>	Adhesion Promoters	<u> </u>
5.437.964	<u> 08/01/95</u>	08/201.146	02/24/94	Stereolithography using vinvl ether-epoxide polya	
5.449.704	09/12/95	<u>Q8/166.763</u>	<u>12/14/93</u>	Photopolymerisable liquid compositions comprist resol and aminotriazine resins	n
5.451.345	09/19/95	08/129.701	09/30/93	Chemical composition	_
5,451,616	<u>09/19/95</u>	08/284.729	<u>08/02/94</u>	Photopolymerisable liquid compositions for form heat curable solid film adhesives	
5,461,088	10/24/95	08/292.654	<u>08/18/94</u>	Liquid radiation-curable formulation, in particular use in stereolithography	í fe
5,468,886	11/21/95	Q8/169.938	12/20/93	(Cyclo)aliphatic epoxy compounds	Ĺ
<u>5.470.689</u>	11/28/95	08/200,982	02/24/94	Polymerisable compositions containing tetraacry	ati
5.476.748	12/19/95	08/166.767	12/14/93	Photosensitive composition	Í.
5,476,749	12/19/95	08/303,563	09/09/94	Photosensitive compositions based on acrylates	Г
5,487,966	01/30/96	08/231.953	04/21/94	Photosensitive composition	٣

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í	Patent	Issued	Application	Filed	Title
	5,494,618	02/27/96.	08/266.829	06/27/94	Increasing the useful range of cationic photoinitiators
					in stereolithography
	5,495,029	02/27/96	08/286.061	08/04/94	(Meth)acrylates containing urethane groups
	5,506,087	04/09/96	08/231.353	04/20/94	Stereolithography using vinv ether based polymers
	5,510,226	04/23/96	08/230.444	04/20/94	Stereolithography using vinyl ether-apoxide polymers
	5,514,519	05/07/96	08/224,503	04/07/94	Production of three-dimensional objects
	5,525,400	06/11/96	07/783.701	<u>05/10/91</u>	Information carrier and process for the production thereof
	5.573.889	11/12/96	08/437.737	Q\$/Q2/95	Process for adjusting the sensitivity to radiation of photopolymerizable compositions
	5,599,651	02/04/97	08/517,888	08/21/95	(Cyclo)aliphatic epoxy compounds
	5.605.941	Q2/25/97	08/304,464	09/12/94	Vinyl ether compounds having additional functional
					groups other than vinvl ether groups and the use thereof in the formulation of curable compositions
	5.620.553	<b>Q4/15/9</b> 7	<u> 08/443,949</u>	05/28/95	Photopolymerisable liquid compositions of bonding friction material to metal
	<u>5.629.133</u>	05/13/97	06/449.172	05/24/95	Liquid radiation-curable formulation in particular for use in stereolithography
2,00	5.645.973	07/08/97	08/592.899	01/29/96	Process for adjusting the sensitivity to radiation of photopolymerizable compositions
•	5,658,712	08/19/97	08/552.643	11/03/95	(Meth)acrylates containing urethane groups
	5.677.107	10/14/97	08/643.790	05/06/96	Production of three-dimensional objects
	5,705,116	01/06/98	08/463.086	06/21/95	increasing the useful range of cationic photoinitiators
					in stereolithography
	<u>5,705,316</u>	01/06/98	08/555.821	11/09/95	Vinvl ether compounds having additional functional
-					groups other than vinyl ether groups and the use thereof in the formulation of curable composition
	5,708,120	01/13/98	08/586.840	01/25/96	Gelled reactive resin composition
	5.783.358	07/21/98	08/611,914	03/06/96	Stabilization of liquid radiation-curable compositions
					against undesired premature polymerization
	5,783,615	07/21/98	08/834,404	04/16/97	Vinyl ether compounds having additional functional
			! !		groups other than vinvl ether groups and the use
	6 702 712	07/25/00	00/6 00 747	00/10/05	thereof in the formulation of curable compositions
	5,783.712	<u>07/21/98</u>	08/689.747	08/13/96	Vinyl ether compounds having additional functional
					groups other than vinyt ether groups and the use thereof in the formulation of curable compositions
	5,859,096	01/12/99	08/920 922	03/19/97	Room temperature storage-stable, heat-curable, low
	<u>26022'020</u>	ATCT 4722	08/820.622	<u>1717177</u>	CTE, one component epoxy resin tooling materia
	5.897.028	04/27/99	08/377.720	01/24/95	Two component adhesive dispensing unit
	5,908,901	06/01/99	08/944.672	10/07/97	Gelled reactive resin compositions
	5,942,182	08/24/99	08/999.527	09/19/97	One component room temperature stable epoxy resin
					compositions for VARTM/RTM systems
	5,942,370	08/24/99	08/893,835	07/11/97	Production of three-dimensional objects
/	5.972.563	10/26/99	<u>08/901,303</u>	07/28/97	Liquid radiation-curable composition, especially for stereolithography
	5,989,475	<u>11/23/99</u>	09/091.452	06/18/98	Process for the stereolithographic preparation of three- dimensional objects using a radiation-curable liquid
375			1		formulation which contains fillers
<u>י</u> י	6,043,323	03/28/00	08/342,955	11/21/94	Diarylates and dimethacrylates
	6.057.389	05/02/00	09/022.754	02/12/98	Curable Compositions
	6,060,544	05/09/00	09/040,989	03/18/98	Chemical compositions
1	6.077.886	05/09/00		10/00/07	Curable Resin Compositions
		07/11/00	08/947,997 09/181,163	10/09/97 10/28/98	Adaptive Compositions
	6.086.795 6.099.787				Adhesive Compositions
	0/072/0/	08/08/00	09/115,086	07/14/98	Process for making three-dimensional articles by stereolithography
	6,100,007	08/08/00	09/055,832	04/06/98	Liquid, radiation-curable composition, especially for
	XIDESINYL.	Market Market	Marmadinah	<u> </u>	producing cured articles by stereolithography having
					high heat deflection temperatures
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PAGE 35/35 * RCVD AT 7/10/2006 4:50:23 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/24 * DNIS:2709907 * CSID:Winston _Strawn * DURATION (mm-ss):18-38

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